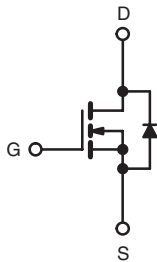


Power MOSFET

PRODUCT SUMMARY	
V_{DS} (V)	500
$R_{DS(on)}$ (Ω)	$V_{GS} = 10\text{ V}$ 0.125
Q_g (Max.) (nC)	230
Q_{gs} (nC)	65
Q_{gd} (nC)	110
Configuration	Single



N-Channel MOSFET



FEATURES

- Super Fast Body Diode Eliminates the Need for External Diodes in ZVS Applications
- Lower Gate Charge Results in Simpler Drive Requirements
- Enhanced dV/dt Capabilities Offer Improved Ruggedness
- Higher Gate Voltage Threshold Offers Improved Noise Immunity
- Lead (Pb)-free Available



Available
RoHS*
COMPLIANT

APPLICATIONS

- Zero Voltage Switching SMPS
- Telecom and Server Power Supplies
- Uninterruptible Power Supplies
- Motor Control Applications

ORDERING INFORMATION	
Package	SUPER-247™
Lead (Pb)-free	IRFPS35N50LPbF SiHFPS35N50L-E3
SnPb	IRFPS35N50L SiHFPS35N50L

ABSOLUTE MAXIMUM RATINGS $T_C = 25\text{ }^\circ\text{C}$, unless otherwise noted				
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-Source Voltage		V_{DS}	500	V
Gate-Source Voltage		V_{GS}	± 30	
Continuous Drain Current	V_{GS} at 10 V	I_D	$T_C = 25\text{ }^\circ\text{C}$	A
			$T_C = 100\text{ }^\circ\text{C}$	
Pulsed Drain Current ^a		I_{DM}	140	
Linear Derating Factor			3.6	W/°C
Single Pulse Avalanche Energy ^b		E_{AS}	560	mJ
Repetitive Avalanche Current ^a		I_{AR}	34	A
Repetitive Avalanche Energy ^a		E_{AR}	45	mJ
Maximum Power Dissipation	$T_C = 25\text{ }^\circ\text{C}$	P_D	450	W
Peak Diode Recovery dV/dt^c		dV/dt	15	V/ns
Operating Junction and Storage Temperature Range		T_J, T_{stg}	- 55 to + 150	°C
Soldering Recommendations (Peak Temperature)	for 10 s		300 ^d	
Mounting Torque	6-32 or M3 screw		10	lbf · in
			1.1	N · m

Notes


- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- Starting $T_J = 25\text{ }^\circ\text{C}$, $L = 0.97\text{ mH}$, $R_G = 25\text{ }\Omega$, $I_{AS} = 34\text{ A}$ (see fig. 12).
- $I_{SD} \leq 34\text{ A}$, $dI/dt \leq 765\text{ A}/\mu\text{s}$, $V_{DD} \leq V_{DS}$, $T_J \leq 150\text{ }^\circ\text{C}$.
- 1.6 mm from case.

* Pb containing terminations are not RoHS compliant, exemptions may apply

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R_{thJA}	-	40	°C/W
Case-to-Sink, Flat, Greased Surface	R_{thCS}	0.24	-	
Maximum Junction-to-Case (Drain)	R_{thJC}	-	0.28	

Note

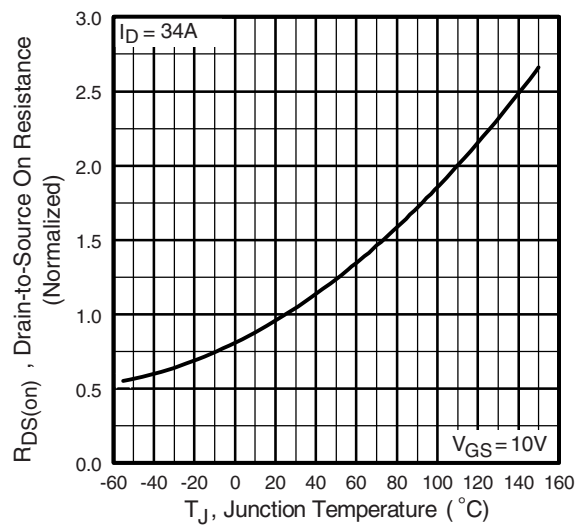
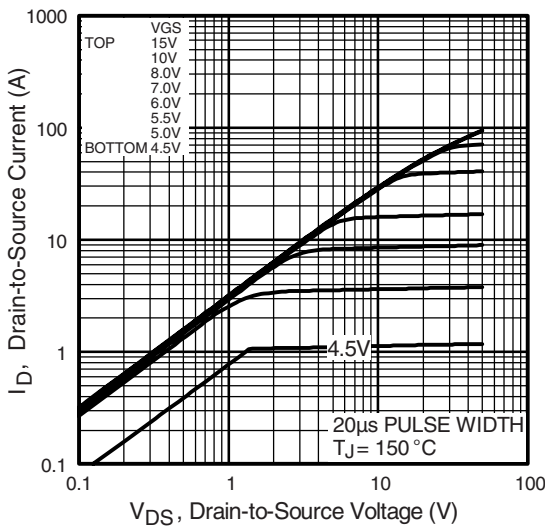
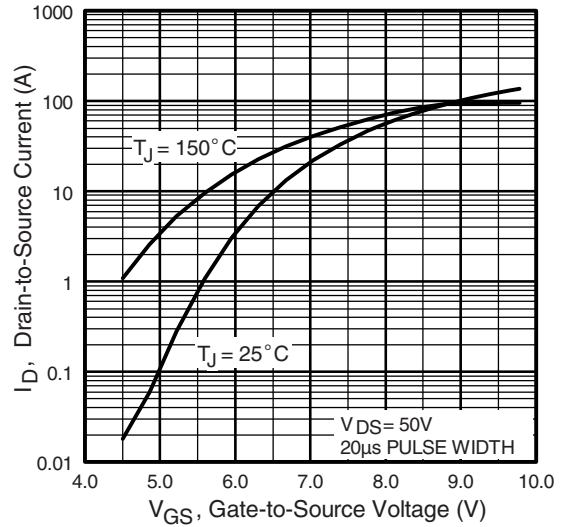
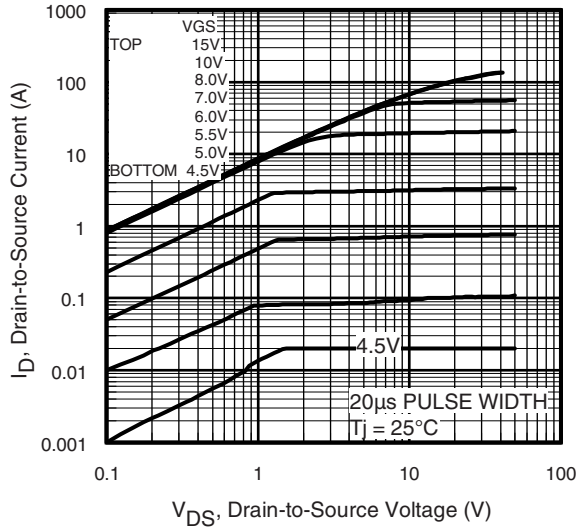
a. R_{th} is measured at T_J approximately 90 °C.

SPECIFICATIONS $T_J = 25\text{ °C}$, unless otherwise noted						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0\text{ V}$, $I_D = 250\text{ }\mu\text{A}$	500	-	-	V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to 25 °C, $I_D = 1\text{ mA}$	-	0.12	-	V/°C
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 250\text{ }\mu\text{A}$	3.0	-	5.0	V
Gate-Source Leakage	I_{GSS}	$V_{GS} = \pm 30\text{ V}$	-	-	± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 500\text{ V}$, $V_{GS} = 0\text{ V}$	-	-	50	μA
		$V_{DS} = 400\text{ V}$, $V_{GS} = 0\text{ V}$, $T_J = 125\text{ °C}$	-	-	2.0	mA
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V}$ $I_D = 20\text{ A}^b$	-	0.125	0.145	Ω
Forward Transconductance	g_{fs}	$V_{DS} = 50\text{ V}$, $I_D = 20\text{ A}^b$	18	-	-	S
Dynamic						
Input Capacitance	C_{iss}	$V_{GS} = 0\text{ V}$, $V_{DS} = 25\text{ V}$, $f = 1.0\text{ MHz}$, see fig. 5	-	5580	-	pF
Output Capacitance	C_{oss}		-	590	-	
Reverse Transfer Capacitance	C_{rss}		-	58	-	
Output Capacitance	C_{oss}	$V_{GS} = 0\text{ V}$	$V_{DS} = 1.0\text{ V}$, $f = 1.0\text{ MHz}$	-	7290	-
			$V_{DS} = 400\text{ V}$, $f = 1.0\text{ MHz}$	-	160	-
Effective Output Capacitance	$C_{oss\text{ eff.}}$	$V_{GS} = 0\text{ V}$	$V_{DS} = 0\text{ V to } 400\text{ V}^c$	-	320	-
Effective Output Capacitance (Energy Related)	$C_{oss\text{ eff. (ER)}}$			-	220	-
Total Gate Charge	Q_g	$V_{GS} = 10\text{ V}$	$I_D = 34\text{ A}$, $V_{DS} = 400\text{ V}$, see fig. 7 and 13 ^b	-	-	230
Gate-Source Charge	Q_{gs}			-	-	65
Gate-Drain Charge	Q_{gd}			-	-	110
Internal Gate Resistance	R_G	$f = 1\text{ MHz}$, open drain		-	1.1	-
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 250\text{ V}$, $I_D = 34\text{ A}$, $R_G = 1.2\text{ }\Omega$, see fig. 10 ^b	-	24	-	ns
Rise Time	t_r		-	100	-	
Turn-Off Delay Time	$t_{d(off)}$		-	42	-	
Fall Time	t_f		-	42	-	
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I_S	MOSFET symbol showing the integral reverse p - n junction diode 	-	-	34	A
Pulsed Diode Forward Current ^a	I_{SM}		-	-	140	
Body Diode Voltage	V_{SD}	$T_J = 25\text{ °C}$, $I_S = 34\text{ A}$, $V_{GS} = 0\text{ V}^b$	-	-	1.5	V
Body Diode Reverse Recovery Time	t_{rr}	$T_J = 25\text{ °C}$, $I_F = 34\text{ A}$	-	170	250	ns
		$T_J = 125\text{ °C}$, $dI/dt = 100\text{ A}/\mu\text{s}^b$	-	220	330	
Body Diode Reverse Recovery Charge	Q_{rr}	$T_J = 25\text{ °C}$, $I_S = 34\text{ A}$, $V_{GS} = 0\text{ V}^b$	-	670	1010	μC
		$T_J = 125\text{ °C}$, $dI/dt = 100\text{ A}/\mu\text{s}^b$	-	1500	2200	
Reverse Recovery Current	I_{RRM}	$T_J = 25\text{ °C}$	-	8.5	-	A
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D)				

Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- Pulse width $\leq 400\text{ }\mu\text{s}$; duty cycle $\leq 2\%$.
- $C_{oss\text{ eff.}}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80 % V_{DS} .
 $C_{oss\text{ eff. (ER)}}$ is a fixed capacitance that stores the same energy as C_{oss} while V_{DS} is rising from 0 to 80 % V_{DS} .

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



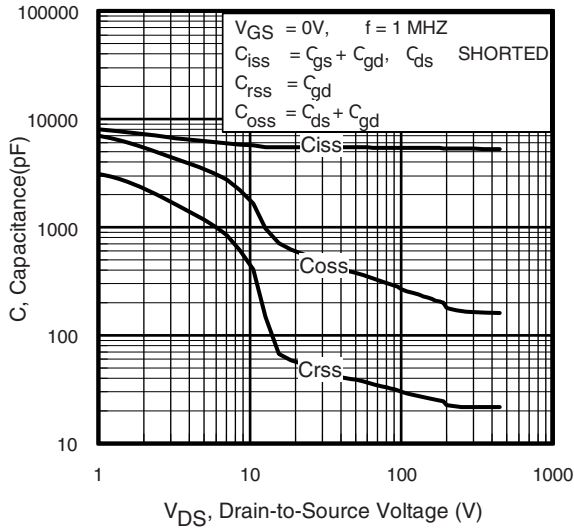


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

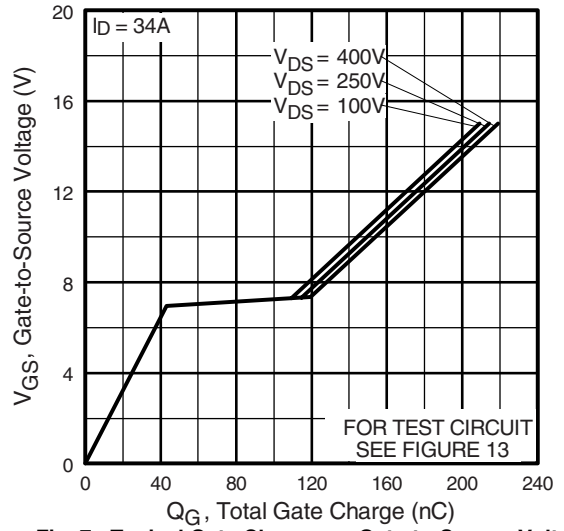


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

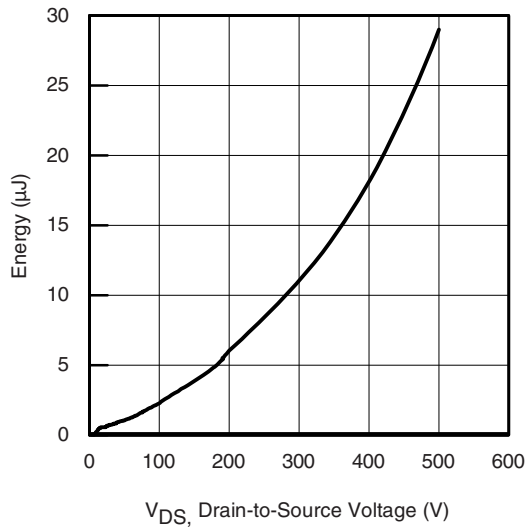


Fig. 6 - Typical Output Capacitance Stored Energy vs. V_{DS}

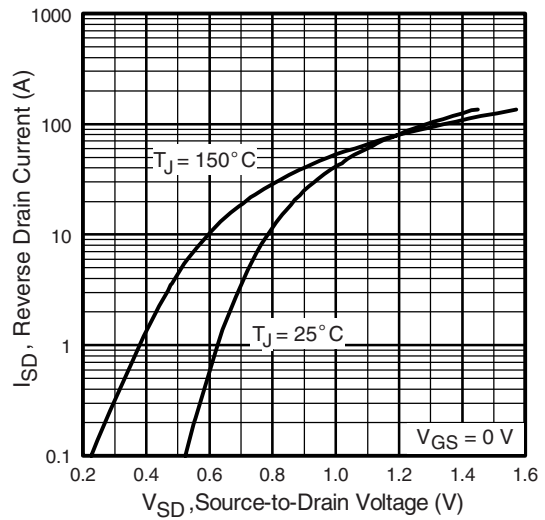


Fig. 8 - Typical Source Drain Diode Forward Voltage

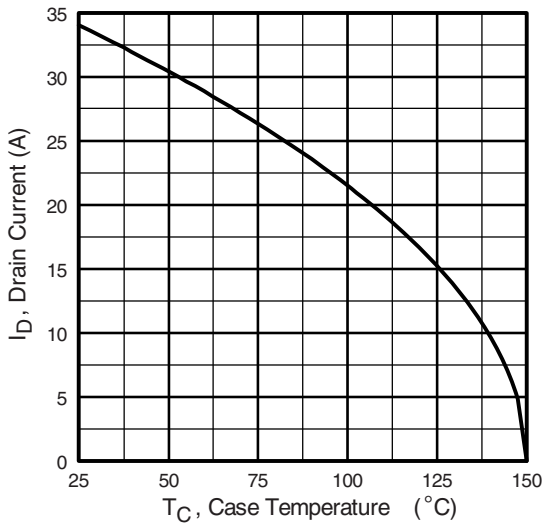


Fig. 9 - Maximum Drain Current vs. Case Temperature

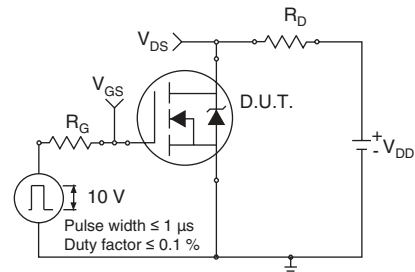


Fig. 10a - Switching Time Test Circuit

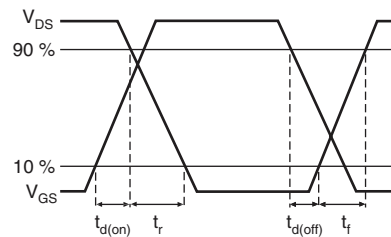


Fig. 10b - Switching Time Waveforms

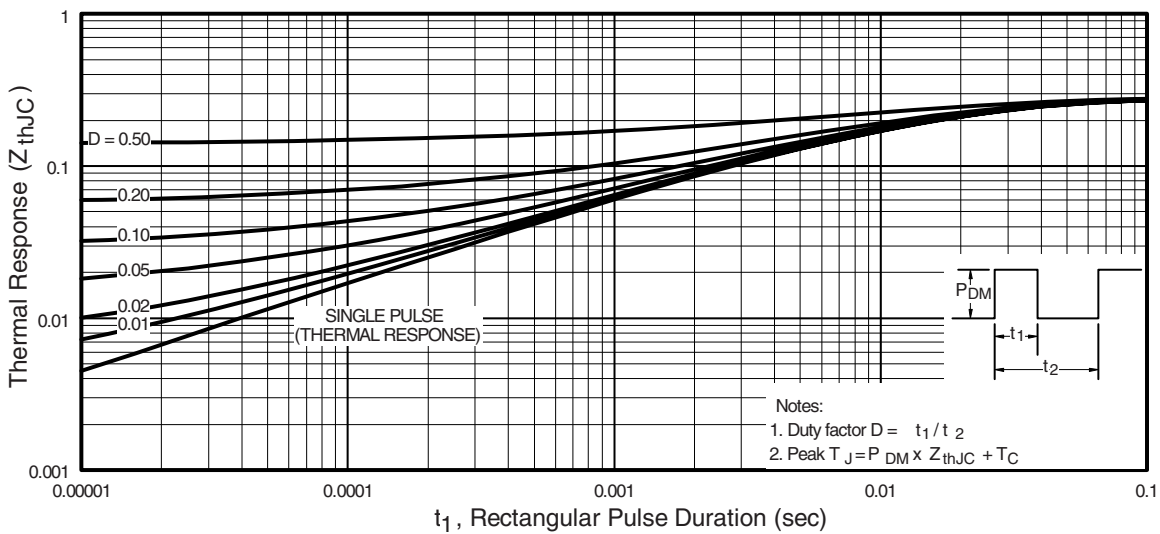


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

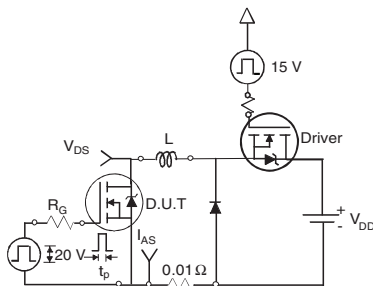


Fig. 12a - Unclamped Inductive Test Circuit

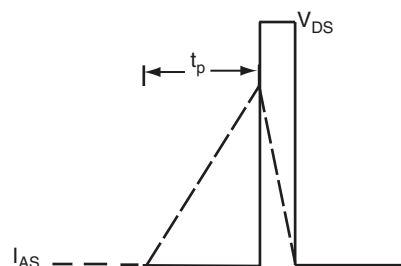


Fig. 12b - Unclamped Inductive Waveforms

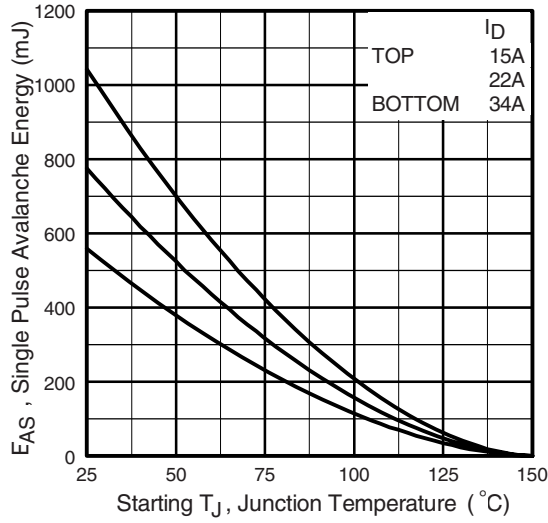


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

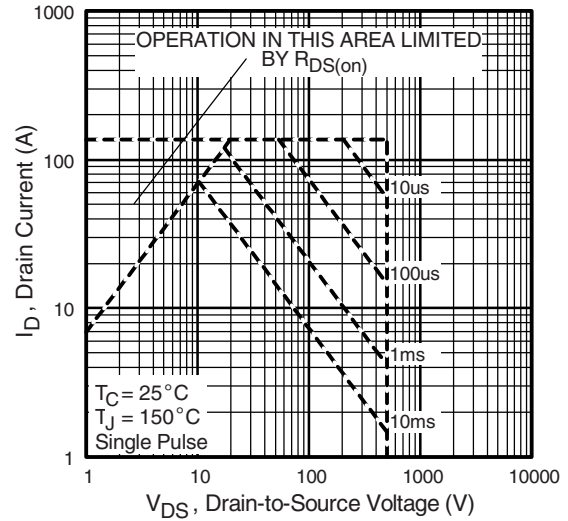


Fig. 12d - Maximum Safe Operating Area

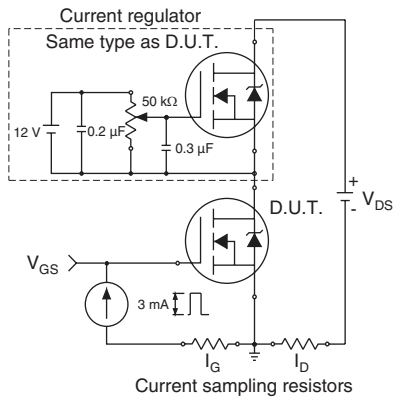


Fig. 13a - Gate Charge Test Circuit

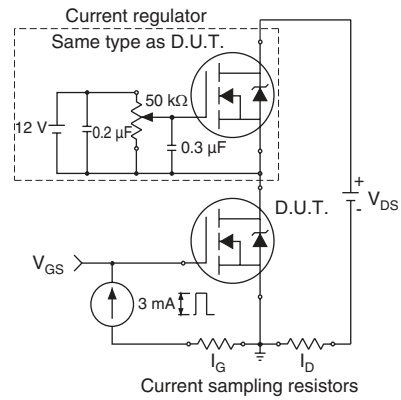
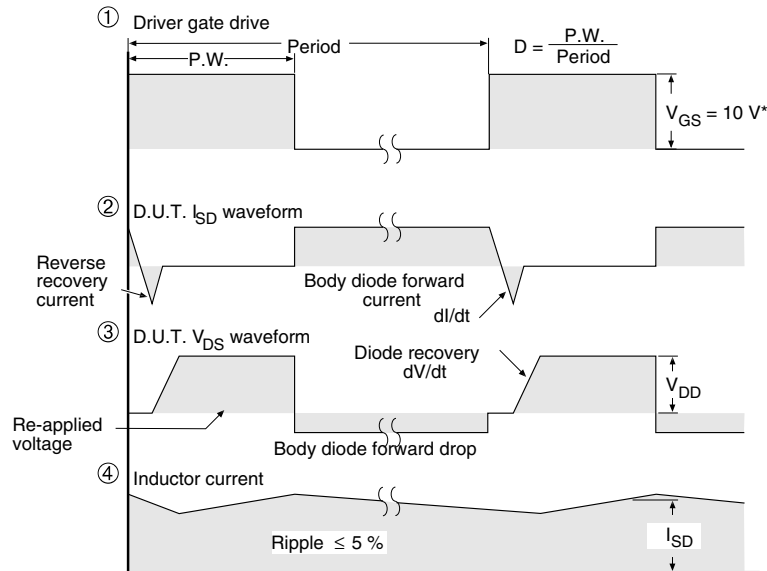
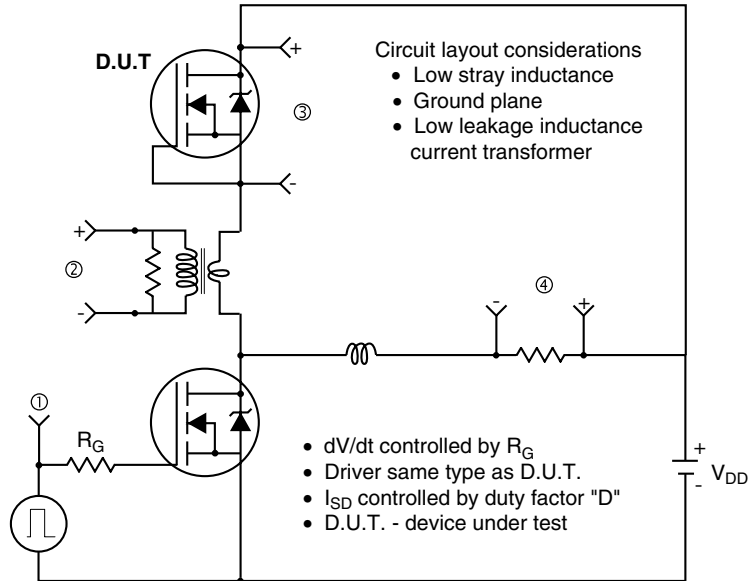


Fig. 13b - Basic Gate Charge Waveform

Peak Diode Recovery dV/dt Test Circuit



* $V_{GS} = 5 V$ for logic level devices

Fig. 14 - For N-Channel

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